

## 2.0 – 5.5 V Low Power 315/433.92/868/915 MHz OOK Receiver

### Features

- Operating frequency: 300 - 480 MHz for CMT2210LH and 300 - 960 MHz for CMT2217LH.
- OOK demodulation
- Data rate: 0.5 - 40 kbps
- Sensitivity: -109 dBm (3.0 kbps), 0.1%BER
- Receiver bandwidth: 330 kHz
- Image rejection ratio: 30 dB
- Maximum input signal: 10 dBm
- Run independently. Input from the antenna and output from data pin.
- No need for register configuration.
- Supply voltage options:
  - 3.0 – 5.5 V (High voltage mode)
  - 2.0 – 3.6 V (Low voltage mode)
- Low power consumption: 4.5 mA@ 433.92 MHz
- RoHS compliant

### Description

CMT2210/17LH is a low power, high performance OOK RF receiver, suitable for wireless applications with 315 / 433.92 / 868 / 915 MHz and nearby frequency points in a ISM band. The CMT2210/17LH is a real plug and play chip. The CMT2210LH operates in a band of 300 - 480 MHz. While the CMT2217LH operates in a band of 300 - 480 MHz by default and can be configured through a CMOSTEK tool to operate in a band of 300 - 480 MHz. The change of RF frequencies can be fulfilled by selecting crystals with different frequencies. The crystal frequencies corresponding to different RF frequencies can be read from the RFPDK interface. This chip is capable of a data rate range of 0.5 – 40 kbps and it is optimized to 1 - 5 kbps as factory setting, ideal for pairing with the low-cost transmitter based on the encoder or MCU. By selecting the VDD5V pin and VDDL pin open circuit or short circuit on the PCB, the CMT2210/17LH can operate in two voltage ranges , namely, 3.0 - 5.5 V and 2.0 - 3.6 V. When operating at 433.92MHz, the chip consumes only 4.5 mA current while achieving the receiver sensitivity of the -109 dBm. the CMT2210/17LH receiver, co-working with the CMT211x/5x receiver, can deliver cost-effective RF application solutions.

### Applications

- Consumer electronics and appliances - lost-cost solution
- Home security and building automation
- Infrared receiver replacement
- Industrial monitoring and control
- Wireless metering reading
- Wireless lighting control system
- Wireless alarm and security system
- Remote Keyless Entry (RKE)

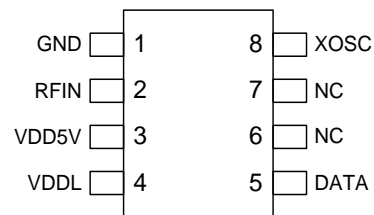
### Ordering information

| Product No.   | Frequency | Packaging | MOQ      |
|---------------|-----------|-----------|----------|
| CMT2210LH-ESR | 433.92MHz | SOP8/Tape | 2,500pcs |
| CMT2217LH-ESB | 868.35MHz | SOP8/Tube | 2,500pcs |

See Section 6 for more order information details.



SOP8



CMT2210/17LH PIN ARRANGEMENT

## Typical Applications

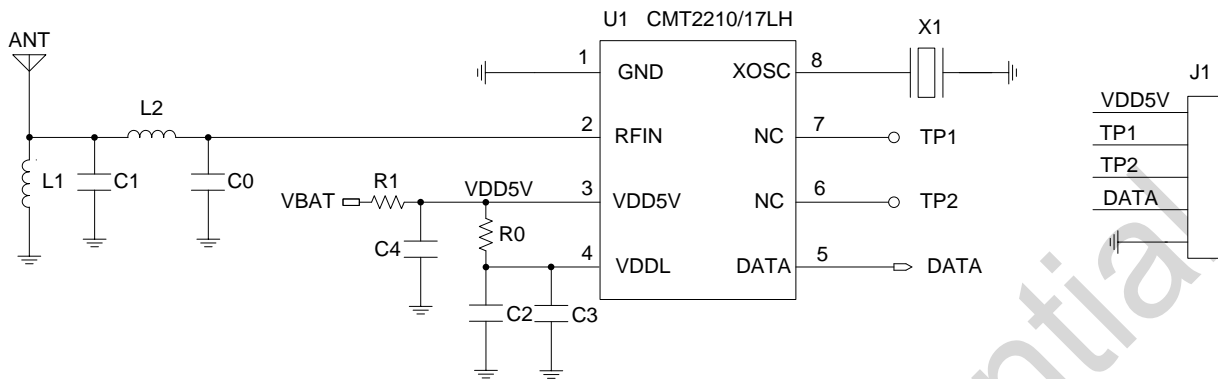


Figure1. CMT2210/17LH Typical Application Schematic

### Notes:

1. When selecting the 3.0 - 5.5 V operating voltage range, do not solder R0, namely, the connection between the VDD5V pin and VDDL pin is broken.
2. When selecting the 2.0 - 3.6 V operating voltage range, R0 is 0, namely, the VDD5V is shorted to the VDDL.
3. The purpose of connecting R1 to VDD-5V is to prevent the chip's power-up in a complex power environment, which achieves better chip protection.
4. J1 is programming pin. Suggest to keep it in product PCB.

Table1. Typical Application BOM

| Symbol | Description  | Value (match to the $\lambda/4$ antenna) |           |           |        | Unit     | Supplier |
|--------|--|--|-----------|-----------|--------|----------|----------|
|        |  | 315MHz                                   | 433.92MHz | 868.35MHz | 915MHz |          |          |
| X1     | $\pm 20$ ppm, SMD32*25 mm,   | 26.2774                                  | 27.1412   | 26.3236   | 26.152 | MHz      | EPSON    |
| L1     | $\pm 10\%$ , 0603 stacked  | 62                                       | 36        | 8.2       | 8.2    | nH       | Sunlord  |
| L2     | $\pm 10\%$ , 0603 stacked  | 68                                       | 36        | 12        | 10     | nH       | Sunlord  |
| C0     | $\pm 0.25$ pF, 0402 NP0, 50 V  | 3  | 3         | -         | -      | pF       | -        |
| C1     | $\pm 0.25$ pF, 0402 NP0, 50 V  | 12                                       | 10        | 7.5       | 7.5    | pF       | -        |
| C2     | $\pm 20\%$ , 0603 X7R, 25 V  | 0.1                                      |           |           |        | uF       | -        |
| C3     | $\pm 20\%$ , 0603 NP0, 50 V  | 470                                      |           |           |        | pF       | -        |
| C4     | $\pm 20\%$ , 0603 X7R, 25 V  | 0.1                                      |           |           |        | uF       | -        |
| R0     | Not solder R0 for 3.0 - 5.0 V operating environment.<br>Not solder R0 for 2 - 3.6 V operating environment. | 0 / NC                                   |           |           |        | $\Omega$ | -        |
| R1     | Protective resistor in series  | 4.7                                      |           |           |        | $\Omega$ |          |
| U1     | CMT2210/17LH, 2.0 - 5.5 V power supply.<br>315/433.92/868/915 MHz OOK receiver.                            | -  |           |           |        | -        | CMOSTEK  |

## Terminology

The terminologies used in this document are described in below.

|               |   |                  |                                     |
|---------------|---|------------------|-------------------------------------|
| <b>AGC</b>    | Automatic Gain Control                              | <b>PC</b>        | Personal computer                   |
| <b>AN</b>     | Application note                                    | <b>PCB</b>       | Printed circuit board               |
| <b>BER</b>    | Bit Error Rate                                      | <b>PLL</b>       | Phase-locked loop                   |
| <b>BOM</b>    | Bill of material                                    | <b>PN9</b>       | Pseudo-Random Binary Sequence       |
| <b>SC</b>     | Basic Spacing between Centers                       | <b>POR</b>       | Power on reset                      |
| <b>BW</b>     | Bandwidth   | <b>PUP</b>       | Power up                            |
| <b>DC</b>     | Direct current                                      | <b>QFN</b>       | Quad Flat Non-lead                  |
| <b>EEPROM</b> | Electrically erasable programmable read-only memory | <b>RF</b>        | Radio frequency                     |
| <b>ESD</b>    | Electro-Static discharge                            | <b>RFPDK</b>     | RF product development kit          |
| <b>SR</b>     | Equivalent series resistance                        | <b>RoHS</b>      | Restriction of Hazardous Substances |
| <b>IF</b>     | Intermediate frequency                              | <b>RSSI</b>      | Received signal strength indicator  |
| <b>LNA</b>    | Low Noise Amplifier                                 | <b>Rx</b>        | Receiving, receiver                 |
| <b>LO</b>     | Local oscillator                                    | <b>SAR</b>       | Successive approximation register   |
| <b>LPOSC</b>  | Low power oscillator                                | <b>SOP</b>       | Small outline package               |
| <b>Max</b>    | Maximum   | <b>SPI</b>       | Serial Peripheral Interface         |
| <b>MCU</b>    | Micro controller unit                               | <b>TH</b>        | Threshold                           |
| <b>Min</b>    | Minimum   | <b>Tx</b>        | Transmitting, transmitter           |
| <b>MOQ</b>    | Minimum Order Quantity                              | <b>Typ</b>       | Typical                             |
| <b>NP0</b>    | Temperature compensation characteristic             | <b>VCO</b>       | Voltage controlled oscillator       |
| <b>NC</b>     | Not connected                                       | <b>XOSC</b>      | Crystal oscillator                  |
| <b>OOK</b>    | On-off keying                                       | <b>XTAL/Xtal</b> | Crystal                             |

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## 1. Electrical Specifications

$V_{DD} = 3.3 \text{ V}$ ,  $T_{OP} = 25 \text{ }^\circ\text{C}$ ,  $F_{RF} = 433.92 \text{ MHz}$ , sensitivity is measured by receiving a PN9 sequence and matching to  $50 \text{ } \Omega$  impedance, 0.1% BER if nothing else stated. All measurement results are obtained using the evaluation board CMT221xLH-EM if nothing else stated.

### 1.1 Recommended Operating Conditions

Table2. Recommended Operating Conditions

| Parameter                | Symbol   | Condition  | Min. | Typ. | Max. | Unit             |
|--------------------------|----------|--|------|------|------|------------------|
| Operating supply voltage | $V_{DD}$ | VDD5V and VDDL are open, the temperature range is between $-40 \text{ }^\circ\text{C}$ and $+85 \text{ }^\circ\text{C}$ .    | 3.0  |      | 5.5  | V                |
|                          |          | VDD5V and VDDL are shorted, the temperature range is between $-40 \text{ }^\circ\text{C}$ and $+85 \text{ }^\circ\text{C}$ . | 2.0  |      | 3.6  | V                |
| Operating temperature    | $T_{OP}$ |  | -40  |      | 85   | $^\circ\text{C}$ |
| Supply voltage slope     |          |  | 1    |      |      | mV/us            |

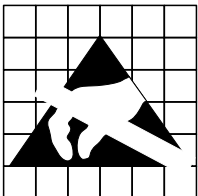
## 1.2 Absolute Maximum Rating

Table3. Absolute Maximum Rating<sup>[1]</sup>

| Parameter                | Symbol           | Condition                      | Min. | Max.                  | Unit |
|--------------------------|------------------|--------------------------------|------|-----------------------|------|
| Supply voltage           | V <sub>DD</sub>  | VDD5V and VDDL are not shorted | -0.3 | 5.5                   | V    |
|                          |                  | VDD5V and VDDL are shorted.    | -0.3 | 3.6                   | V    |
| Interface voltage        | V <sub>IN</sub>  |                                | -0.3 | V <sub>DD</sub> + 0.3 | V    |
| Junction temperature     | T <sub>J</sub>   |                                | -40  | 125                   | °C   |
| Storage temperature      | T <sub>STG</sub> |                                | -50  | 150                   | °C   |
| Welding temperature      | T <sub>SDR</sub> | Last for at least 30 seconds   |      | 255                   | °C   |
| ESD grade <sup>[2]</sup> |                  | Human Body Model (HBM)         | -2   | 2                     | kV   |
| Latching current         |                  | @ 85 °C                        | -100 | 100                   | mA   |

Notes:

- [1]. Exceeding the *Absolute Maximum Ratings* may cause permanent damage to the equipment. This value is a pressure rating and does not imply that the function of the equipment is affected under this pressure condition, but if it is exposed to absolute maximum ratings for extended periods of time, it may affect equipment reliability.
- [2]. CMT2210/17LH is a high performance RF IC. The operation and assembly of this chip should only be performed on a workbench with good ESD protection.



**Warning! It is ESD sensitive device. In the operation of the chip, the user should pay attention to ESD precautions, so as to avoid the chip performance degradation or loss of function.**

## 1.3 Receiver

Table4. Receiver Specification

| Parameter                           | Symbol         | Condition   | Min. | Typ.                 | Max. | Unit |
|-------------------------------------|----------------|---|------|----------------------|------|------|
| Frequency range                     | $F_{RF}$       | CMT2210LH, CMT2217LH  | 300  |                      | 480  | MHz  |
|                                     |                | CMT2217LH   | 600  |                      | 960  | MHz  |
| Data rate                           | DR             |   | 0.5  |                      | 40   | kbps |
| Sensitivity                         | $S_{315}$      | $F_{RF} = 315$ MHz, DR = 3 kbps, BER = 0.1%   |      | -109                 |      | dBm  |
|                                     | $S_{433.92}$   | $F_{RF} = 433.92$ MHz, DR = 3 kbps, BER = 0.1%  |      | -109                 |      | dBm  |
|                                     | $S_{868.35}$   | $F_{RF} = 868.35$ MHz, DR = 3 kbps, BER = 0.1%  |      | -108                 |      | dBm  |
|                                     | $S_{915}$      | $F_{RF} = 915$ MHz, DR = 3 kbps, BER = 0.1%   |      | -108                 |      | dBm  |
| Input saturation level              | $P_{LVL}$      |   |      | 10                   |      | dBm  |
| Operating current                   | $I_{DD315}$    | $F_{RF} = 315$ MHz  |      | 4.2                  |      | mA   |
|                                     | $I_{DD433.92}$ | $F_{RF} = 433.92$ MHz   |      | 4.5                  |      | mA   |
|                                     | $I_{DD868.35}$ | $F_{RF} = 868.35$ MHz   |      | 5.8                  |      | mA   |
|                                     | $I_{DD915}$    | $F_{RF} = 915$ MHz  |      | 6.2                  |      | mA   |
| Frequency synthesizer settling time | $T_{LOCK}$     | Start from the stable crystal oscillation.  |      | 150                  |      | us   |
| Block resistance;                   | BI             | $\pm 1$ MHz, continuous wave interference   |      | 32                   |      | dB   |
|                                     |                | $\pm 2$ MHz, continuous wave interference   |      | 42                   |      | dB   |
|                                     |                | $\pm 10$ MHz, continuous wave interference  |      | 61                   |      | dB   |
| Input 3rd order intercept point     | IIP3           | Dual tone test with frequency offset of 1 MHz and 2 MHz, at the maximum system gain setting |      | -23                  |      | dBm  |
| Receiver bandwidth <sup>[1]</sup>   | $BW_{315}$     | $F_{RF} = 315$ MHz  |      | 240                  |      | kHz  |
|                                     | $BW_{433.92}$  | $F_{RF} = 433.92$ MHz   |      | 330                  |      | kHz  |
|                                     | $BW_{868.35}$  | $F_{RF} = 868.35$ MHz   |      | 240                  |      | kHz  |
|                                     | $BW_{915}$     | $F_{RF} = 915$ MHz  |      | 240                  |      | kHz  |
| Receiver startup time               | $T_{START-UP}$ | From power-up to receiving  |      | $4.5+T_{XTAL}^{[2]}$ |      | ms   |

Notes:

[1]. The receiver supports 4 bandwidth options, namely 120 / 240 / 330 / 400 kHz. When the chip is operating at 433.92 MHz, the default receiving bandwidth is configured as 330 kHz, and the default receiving bandwidth for the other frequencies is 240 kHz. If necessary, users can select the required receiving bandwidth via RFPDK.

[2].  $T_{XTAL}$  is the oscillation time of crystal, which is largely related to the crystal itself.



## 1.4 Crystal Oscillator

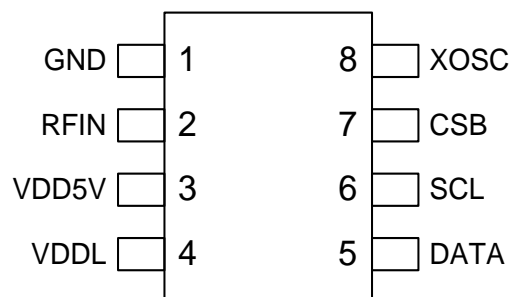
**Table5. Crystal Oscillator Specification**

| Parameter                      | Symbol           | Condition               | Min. | Typ.    | Max. | Unit     |
|--------------------------------|------------------|-------------------------|------|---------|------|----------|
| Crystal frequency [1]          | $F_{XTAL315}$    | $F_{RF} = 315$ MHz      |      | 26.2774 |      | MHz      |
|                                | $F_{XTAL433.92}$ | $F_{RF} = 433.92$ MHz   |      | 27.1412 |      | MHz      |
|                                | $F_{XTAL868.35}$ | $F_{RF} = 868.35$ MHz   |      | 26.3236 |      | MHz      |
|                                | $F_{XTAL915}$    | $F_{RF} = 915$ MHz      |      | 26.1522 |      | MHz      |
| Crystal frequency accuracy [2] |                  |                         |      | ±20     |      | ppm      |
| Load capacitor [3]             | $C_{LOAD}$       | SMD32*25 mm packaging   |      | 15      |      | pF       |
|                                |                  | 49USSMDor 49S packaging |      | 22      |      | pF       |
| Crystal equivalent resistance  | $R_m$            |                         |      |         | 60   | $\Omega$ |
| Crystal start-up time [4]      | $T_{XTAL}$       |                         |      | 400     |      | us       |

**Notes:**

- [1]. The CMT2210/17LH can use the external reference clock to drive the XOSC pin through the coupling capacitor. The peak value of the external clock signal is between 0.3 and 0.7 V.
- [2]. The value includes (1) initial error (2) crystal load (3) aging and (4) frequency change with temperature. The acceptable crystal frequency error is limited by the receiver's bandwidth and the RF frequency deviation between the transmitter and the receiver.
- [3]. Due to the difference in parasitic capacitance caused by different crystal packaging, it is recommended to select crystals with different load capacitance values depending on the package used.
- [4]. The parameter is largely related to the crystal.

## 2. Pin Description



**Figure2. CMT2210/17LH Pin Arrangement**

Table6. CMT2210/17LH Pin Description

| Pin # | Name  | I/O | Function Description  |
|-------|-------|-----|---|
| 1     | GND   | I   | GND   |
| 2     | RFIN  | I   | The RF signal is input to the LNA   |
| 3     | VDD5V | I   | Power input   |
| 4     | VDDL  | O   | Power output  |
| 5     | DATA  | O   | The programming DATA pin and received signal output pin. Suggest keep this programming point. |
| 6     | SCL   | I   | The programming SCL pin. Suggest keep this programming point.                                 |
| 7     | CSB   | I   | The programming CSB pin. Suggest keep this programming point.                                 |
| 8     | XOSC  | I   | Crystal oscillator input, or external reference clock input                                   |

### 3. Typical Performance

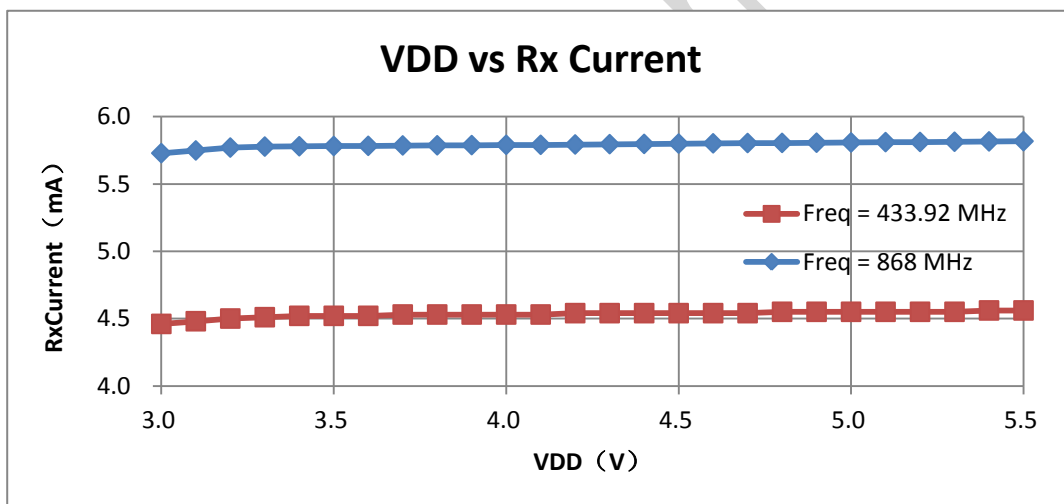


Figure3. Rx Current vs. Supply Voltage

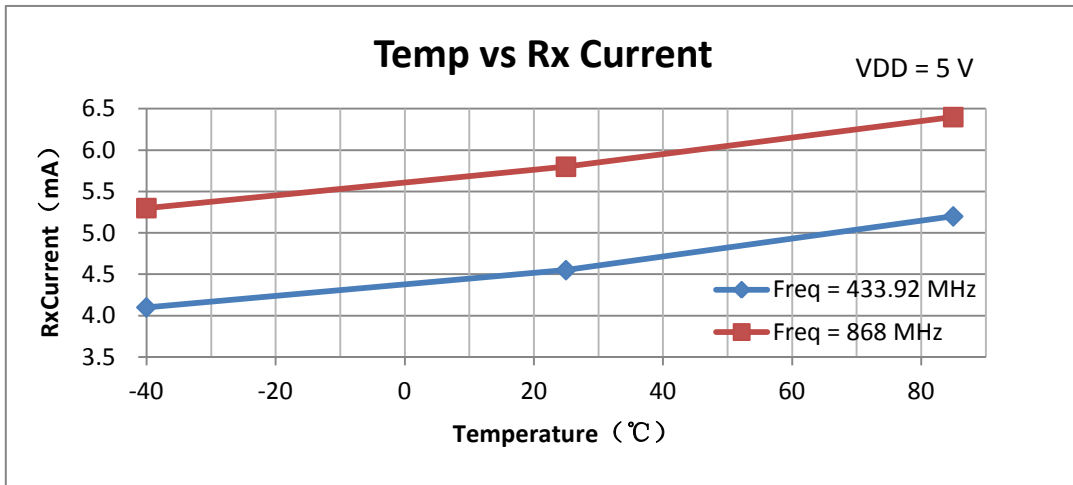


Figure4. Rx Current vs. Operating Temperature

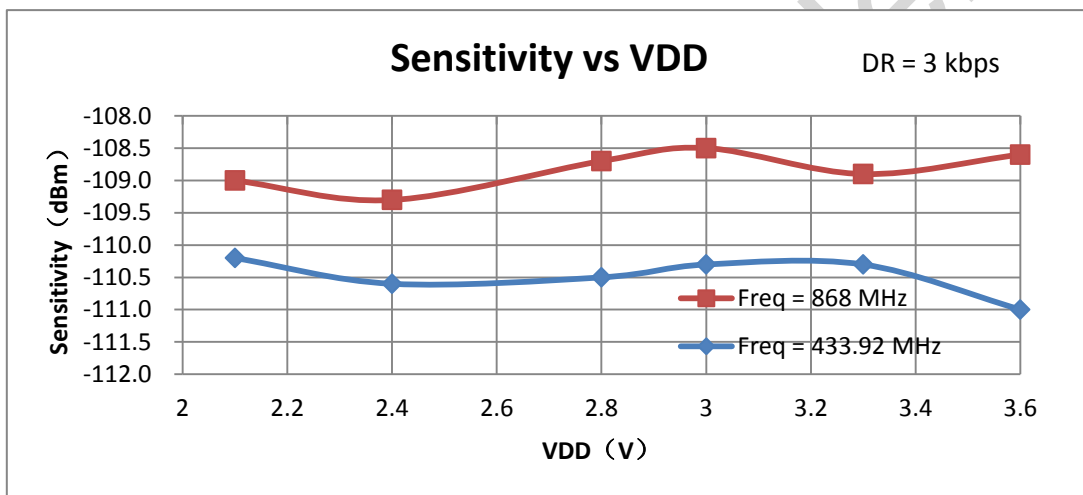


Figure5. Sensitivity vs. Supply Voltage

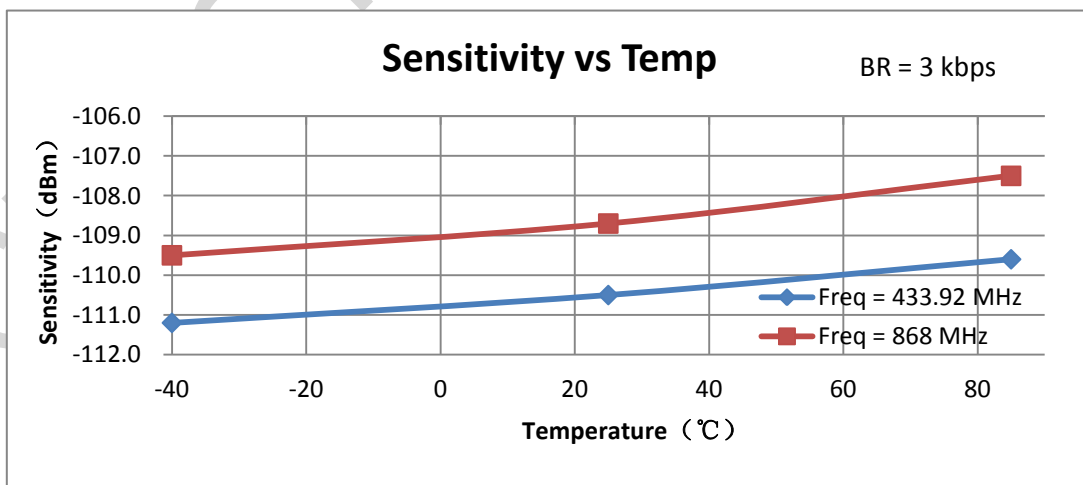


Figure6. Sensitivity vs. Operating Temperature

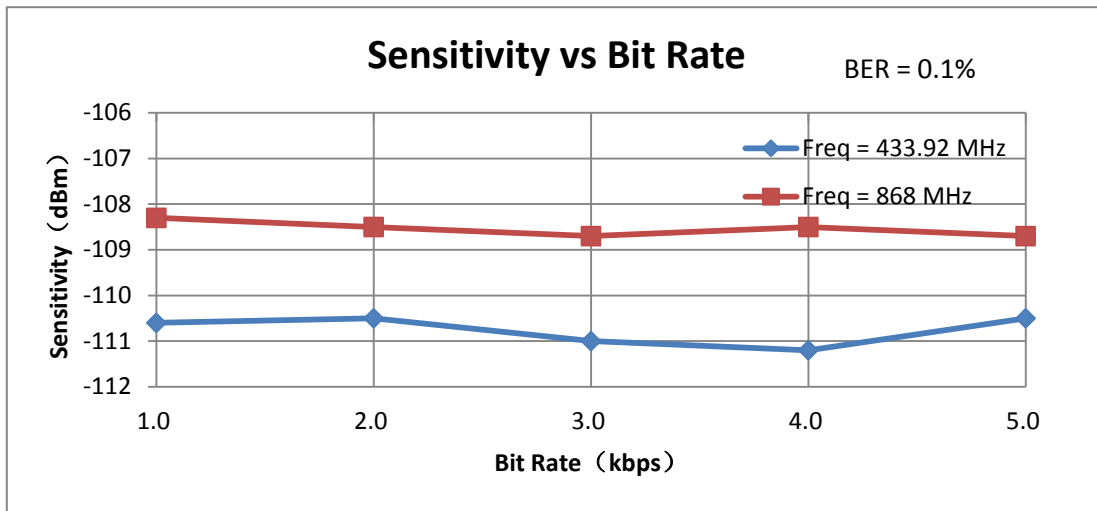


Figure7. Sensitivity vs. Bit Rate

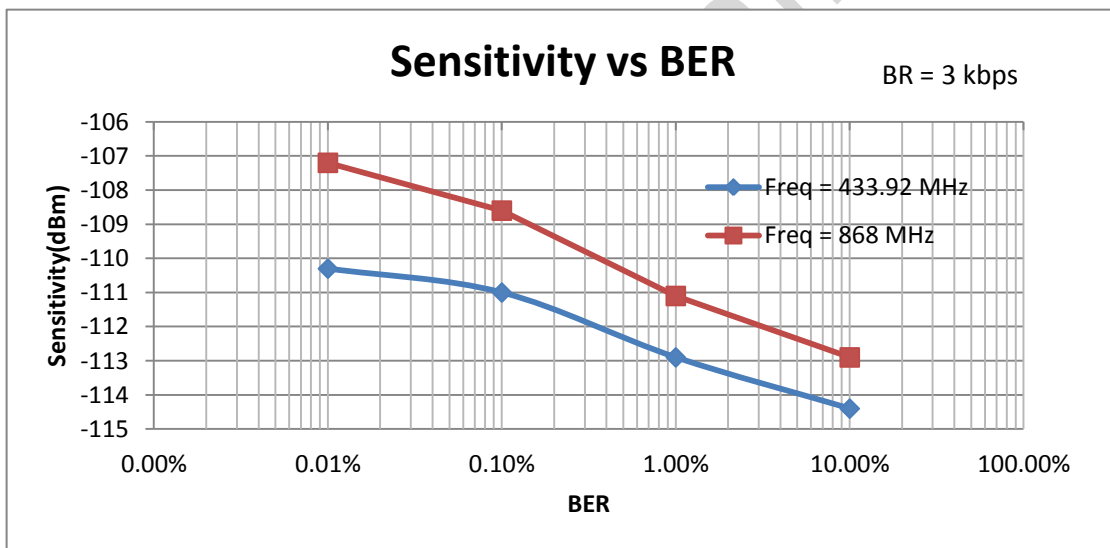
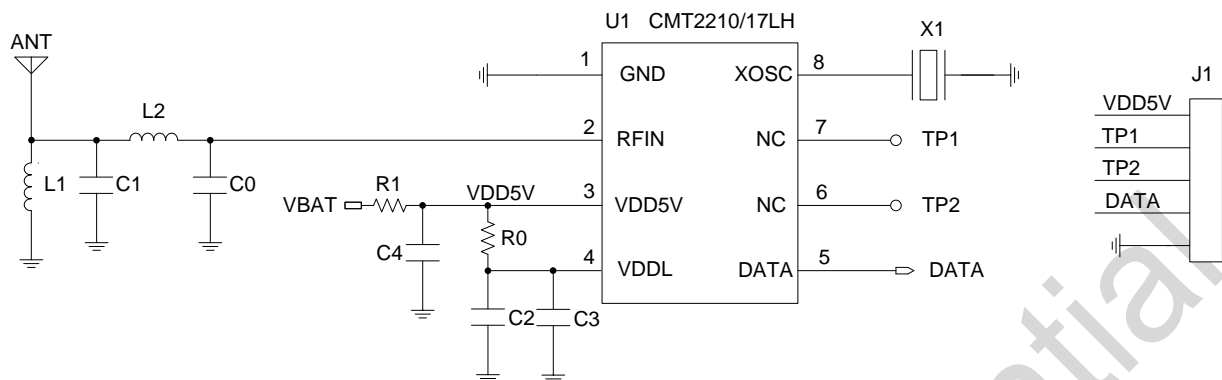


Figure8. Sensitivity vs. Bit Error Rate

## 4. Typical Application Schematic



**Figure9. Typical Application Schematic Diagram**

Notes:

[1]. The PCB layout rules are as below

- Try to design the large and continuous ground.
- Place L1, L2, C0 and C1 as close as possible to the chip, to reduce the distribution parameters of LNA and its loop and prevent a long loop, which may introduce noise signals.
- Place crystal X1 as close as possible to the chip, so as to shorten the track between the crystal and the chip.
- Place grounding vias along the edge of the plate as many as possible to reduce the radiation of the RF signal and the interference from outside. The spacing of the vias should be much smaller than 1/10 wavelength (operating frequency).
- Place C2, C3, and C4 near to chip to achieve better filtering results.
- The metal case of the crystal should be grounded.

[2]. Please refer to *AN158 CMT221xLH schematic and the PCB layout guidelines* for more details on the PCB design.

Table7. Typical Application BOM Matching 315 / 433.92 MHz

| Symbol | Description  | Value(Match to the $\lambda/4$ antenna) |           |           |         | Unit     | Supplier |
|--------|--|---|-----------|-----------|---------|----------|----------|
|        |  | 315MHz                                  | 433.92MHz | 868.35MHz | 915MHz  |          |          |
| X1     | $\pm 20$ ppm, SMD32*25 mm, crystal   | 26.2774                                 | 27.1412   | 26.3236   | 26.1522 | MHz      | EPSON    |
| L1     | $\pm 10\%$ , 0603 stacked inductor   | 62                                      | 36        | 8.2       | 8.2     | nH       | Sunlord  |
| L2     | $\pm 10\%$ , 0603 stacked inductor   | 68                                      | 36        | 12        | 10      | nH       | Sunlord  |
| C0     | $\pm 0.25$ pF, 0402 NP0, 50 V  | 3                                       | 3         | -         | -       | pF       | -        |
| C1     | $\pm 0.25$ pF, 0402 NP0, 50 V  | 12                                      | 10        | 7.5       | 7.5     | pF       | -        |
| C2     | $\pm 20\%$ , 0603 X7R, 25 V  | 0.1                                     |           |           |         | $\mu$ F  | -        |
| C3     | $\pm 20\%$ , 0603 NP0, 50 V  | 470                                     |           |           |         | pF       | -        |
| C4     | $\pm 20\%$ , 0603 X7R, 25 V  | 0.1                                     |           |           |         | $\mu$ F  | -        |
| R0     | Not solder R0 for 3.0 - 5.0 V operating environment.                         | 0 / NC                                  |           |           |         | $\Omega$ | -        |
| R1     | Series protection resistor   | 4.7                                     |           |           |         | $\Omega$ | -        |
| U1     | CMT2210/17LH, 2.0 – 5.0 V power supply, 315/433.92/868/915 MHz OOK receiver. | -                                       |           |           |         | -        | CMOSTEK  |

### 5. Function Description

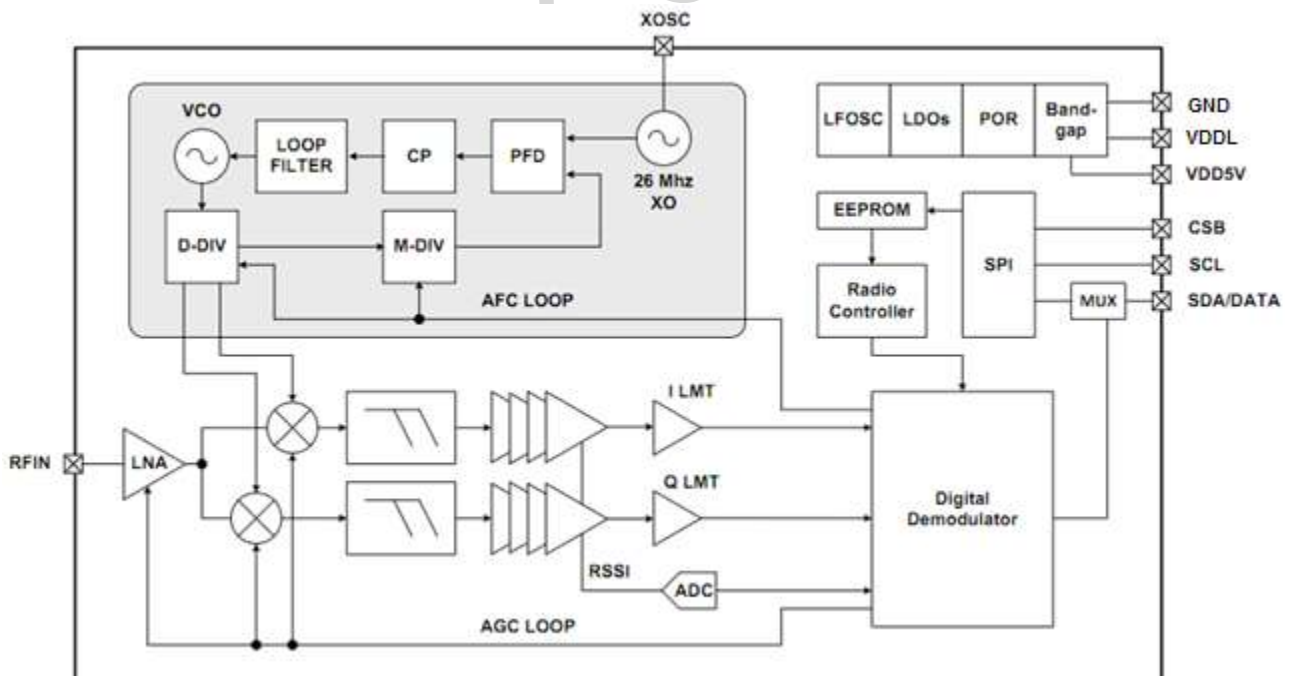


Figure10. Function Module Diagram

## 5.1 Overview

The CMT2210/17LH is a digital-analog hybrid receiver. The product adopts the 26 MHz crystal to provide the reference frequency and digital clock for PLL, supports OOK demodulation output with a data rate of 0.5 - 40 kbps, and supports the periodic reset with the period time configurable, which can avoid chip crash caused by various external reasons. The CMT2210/17LH supports 2 operating voltages applicable for both 5V and 3V application systems.

The chip uses LNA+MIXER+IFFILTER+LIMITTER+PLL's low intermediate frequency structure to achieve the wireless reception function below Sub-1G frequency. The analog front-end is responsible for mixing RF signals into intermediate frequency, and converting the real time RSSI into the 8-bit digital signal through SAR-ADC, and sending them to the interior to perform the OOK demodulation and correlation processing. At the same time, the internal circuit will mix the intermediate frequency signal down to the zero frequency (baseband) and perform a series of filtering and judging process, while AGC dynamically controls the analog front-end. Finally, the original signal is demodulated and output through the DATA pin.

The parameters of the chip are stored in an internal EEPROM, and users can modify or adjust the operating parameters of the chip by the RFPDK.

## 5.2 Demodulation Mode, Frequency and Data Rate

CMT2210/17LH supports the OOK demodulation of 1.0 - 5.0 kbps data rate. The CMT2217LH supports 2 free ISM bands, 300 - 480 MHz and 600 - 960 MHz. The CMT2210LH supports the band of 300 - 480 MHz only. The demodulation mode, frequency and data rate of the CMT2210/17LH is listed in the below table.

**Table 9. Demodulation Mode, Frequency and Data Rate**

| Parameter                 | Value                  | Unit |
|---------------------------|------------------------|------|
| Demodulation mode         | OOK                    | -    |
| CMT2210LH frequency range | 300 – 480              | MHz  |
| CMT2217LH frequency range | 300 – 480<br>600 - 960 | MHz  |
| Data rate                 | 0.5 – 40               | kbps |

## 5.3 Function Module Description

### 5.3.1 RF Front-end and Automatic Gain Control

CMT2210/17LH is an OOK modulated receiver with a low intermediate frequency architecture. The receiver's RF front-end consists of a low-noise amplifier (LNA), an I / Q mixer (Mixer), an intermediate frequency filter (IF Filter), and a wideband power detector (WB Power Detector). The RF front-end amplifies and converts the RF input signals from the antenna to the intermediate frequency for further processing.

Through the broadband power detector and RF attenuation network of RF front-end, the automatic gain control (AGC) loop can adjust the RF front-end gain. The chip can also achieve optimal system linearity, selectivity and sensitivity even under the condition of strong interference outside the band.

By using a low-cost matching circuit, the LNA input can be matched to 50  $\Omega$  or other types of antennas.

### **5.3.2 Intermediate Frequency (IF) Filter**

The signal from the RF front-end is filtered by an integrated 3rd order band pass image rejection filter. When the device operates at 433.92 MHz, the intermediate frequency bandwidth is 330 kHz. The center frequency and bandwidth will be adjusted automatically according to the selected crystal frequency.

### **5.3.3 Received Signal Strength Indicator**

The output signal of the IF filter is amplified by the cascade I/Q logarithmic amplifier, and then sent to the demodulator for demodulation. I/Q dual logarithmic amplifiers include the received signal strength indicator (RSSI). The indicator generates the DC level in proportion to the input signal level within the I/Q path. The sum of levels of these two paths is used as an indication of the received signal strength, with a dynamic range of more than 66 dB.

### **5.3.4 Successive Approximation Register**

The 8-bit SAR-ADC in CMT2210/17LH transforms the RSSI output into the digital signal for OOK demodulation.

### **5.3.5 Crystal Oscillator**

The CMT2210/17LH uses a single-ended crystal oscillator circuit with the required load capacitance integrated within the chip. Recommend using crystals with an accuracy of + 20 ppm, an equivalent resistance (ESR) < 60 and a load capacitance (CLOAD) of 15pF.

If there is a suitable clock source in the application system, which can be used as the reference clock of CMT2210/17LH, users can drive the XOSC pin of the chip through the DC blocking capacitor. This will help save one crystal to further reduce the system cost. Recommend the clock source with a peak to peak value between 0.3 V to 0.7V (at the XOSC pin).

### **5.3.6 Frequency Synthesizer**

The frequency synthesizer is used to generate the local oscillator (LO) frequency required for the I/Q mixer. Through the reference clock provided by a crystal or external clock source, the frequency synthesizer can generate the required operating frequencies. The internal high performance VCO operates at twice of the LO frequency. The chip can operate stably upon power-up with no need for external inductors.



## 6. Ordering Information

Table10. CMT2210/17LH Ordering Information

| Model                        | Description   | Packaging | Packaging Option | Operating Condition                   | Minimum Order Quantity |
|------------------------------|---|-----------|------------------|---------------------------------------|------------------------|
| CMT2210LH-ESR <sup>[1]</sup> | 2.0 - 5.5 V Power supply,<br>300 - 480 MHz OOK receiver | SOP8      | Tape & tray      | 2 – 3.6 V<br>3 – 5.5 V<br>-40 – 85 °C | 2,500                  |
| CMT2210LH-ESB <sup>[1]</sup> | 2.0 - 5.5 V Power supply,<br>300 - 480 MHz OOK receiver | SOP8      | Tube             | 2 – 3.6 V<br>3 – 5.5 V<br>-40 – 85 °C | 1,000                  |
| CMT2217LH-ESR <sup>[1]</sup> | 2.0 – 5.5 V Power supply,<br>300 - 960 MHz OOK receiver | SOP8      | Tape & tray      | 2 – 3.6 V<br>3 – 5.5 V<br>-40 – 85 °C | 2,500                  |
| CMT2217LH-ESB <sup>[1]</sup> | 2.0 – 5.5 V Power supply,<br>300 - 960 MHz OOK receiver | SOP8      | Tube             | 2 – 3.6 V<br>3 – 5.5 V<br>-40 – 85 °C | 1,000                  |

**Notes:**

[1]. "E" represents the extended industrial grade. The temperature range is from -40 to +85.  
 "S" represents the SOP8 packaging.  
 "R" represents the tape reel packing. MOQ is 2500pcs; "B" represents the tube packing. MOQ is 1000pcs.

Please visit [www.cmostek.com](http://www.cmostek.com) for more product/product line information.

Please contact [sales@cmotek.com](mailto:sales@cmotek.com) or your local sales representative for sales or pricing requirements.

## 7. Packaging Information

The packaging information of the CMT2210/17LH is shown in the below figure.

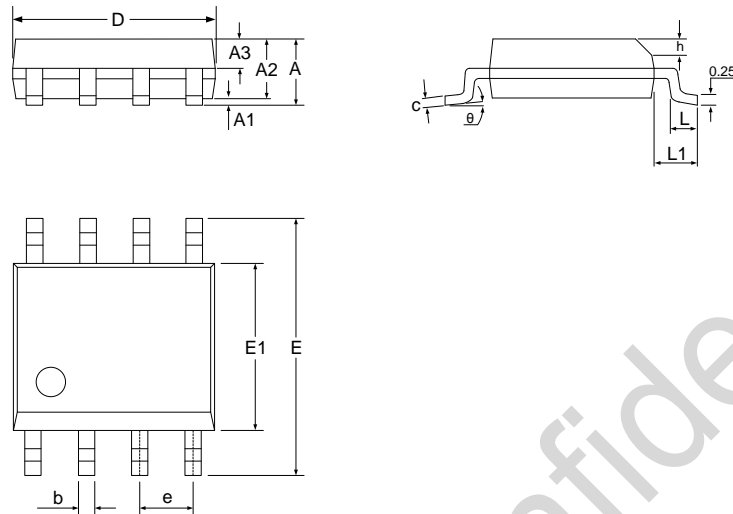


Figure11. SOP8 Packaging

Table11. SOP8 Packaging Scale

| Symbol   | Scale (mm) |      |       |
|----------|------------|------|-------|
|          | Min.       | Typ. | Max.  |
| A        | -          | -    | 1.75  |
| A1       | 0.10       | -    | 0.225 |
| A2       | 1.30       | 1.40 | 1.50  |
| A3       | 0.60       | 0.65 | 0.70  |
| b        | 0.39       | -    | 0.48  |
| c        | 0.21       | -    | 0.26  |
| D        | 4.70       | 4.90 | 5.10  |
| E        | 5.80       | 6.00 | 6.20  |
| E1       | 3.70       | 3.90 | 4.10  |
| e        | 1.27 BSC   |      |       |
| h        | 0.25       | -    | 0.50  |
| L        | 0.50       | -    | 0.80  |
| L1       | 1.05 BSC   |      |       |
| $\theta$ | 0          | -    | 8°    |

## 8. Top Marking

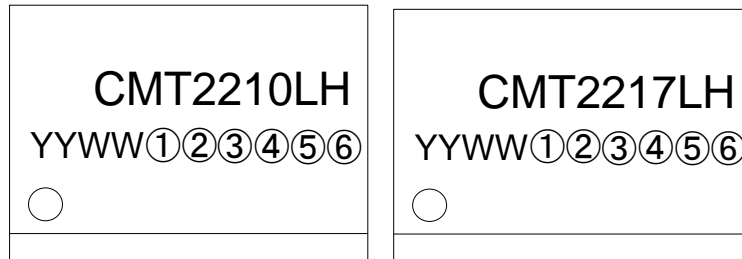


Figure12. CMT2210LH and CMT2217LH Top Marking

Table12. CMT2210/17LH Top Marking Description

|                       |  |
|-----------------------|--|
| <b>Marking method</b> | Laser  |
| <b>Pin 1 mark</b>     | Circle diameter = 0.5 mm   |
| <b>Font height</b>    | 0.6 mm, right aligned.   |
| <b>Font width</b>     | 0.3 mm   |
| <b>Line 1 marking</b> | CMT2210LH represents the model CMT2210LH<br>CMT2217LH represents the model CMT2217LH   |
| <b>Line 2 marking</b> | YYWW is the date code set by the packaging factory. YY represents the last 2 digits of the year. WW represents the manufacturing week.<br>①②③④⑤⑥ represents the internal tracking coding |

## 9. Reference Documents

Table13. CMT2210/17LH Related Documents

| Doc No. | Name   | Description   |
|---------|--|---|
| AN157   | CMT221xLH Configuration Guideline            | Introduce the configuring CMT2210LH and CMT2217LH details by RFPDK  |
| AN158   | CMT221xLH schematic and PCB layout guideline | Introduce CMT2210LH and CMT2217LH schematic and PCB layout design rules, RF matching network and other layout considerations. |

## 10. Revise History

Table14. Revise History Records

| Version | Chapter | Modification descriptions                             | Date       |
|---------|---------|---|------------|
| 0.1     | All     | Initial release version                               | 2017-08-10 |
| 0.2     | All     | Fix spelling and grammar mistakes                     | 2017-09-21 |
| 0.3     | 1       | Page 2, Table 1, update supply voltage to 3.0 - 5.5 V | 2018-02-07 |
| 0.5     | All     | Add chip model CMT2217LH and related information      | 2018-08-22 |

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## 11. Contacts

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